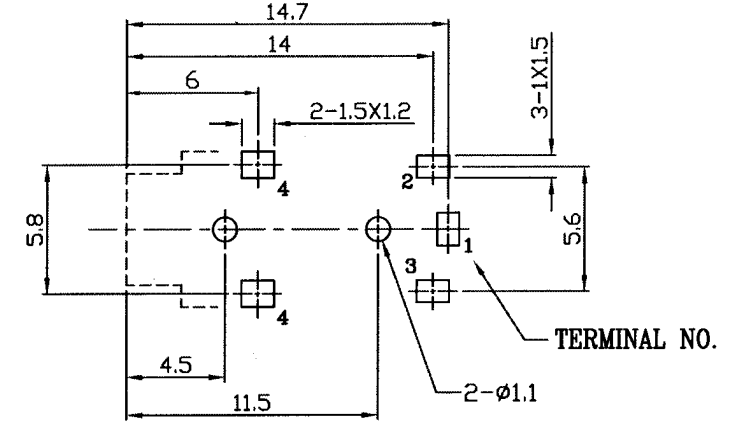
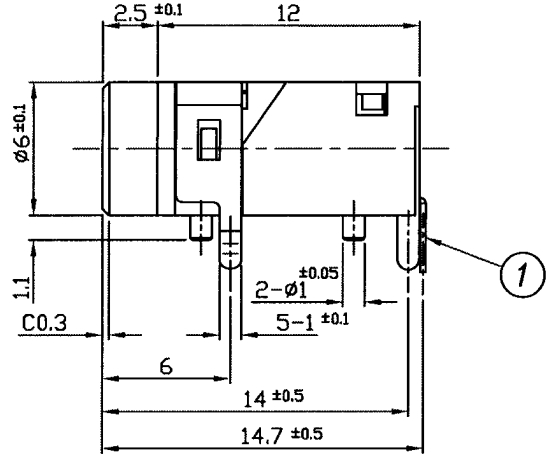
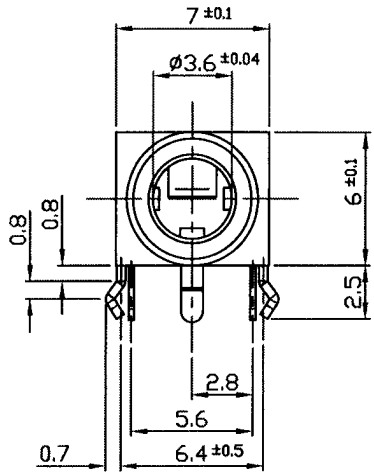
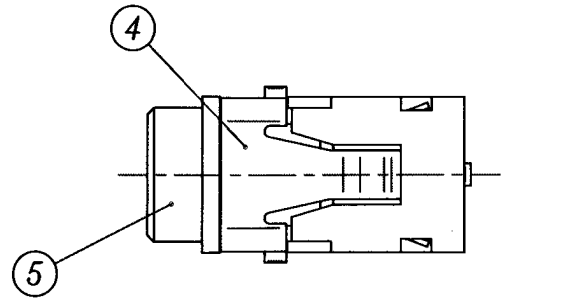
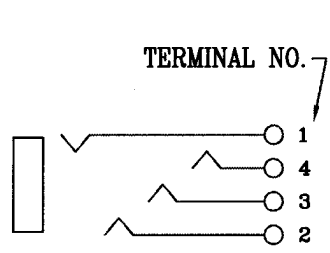


REVISION

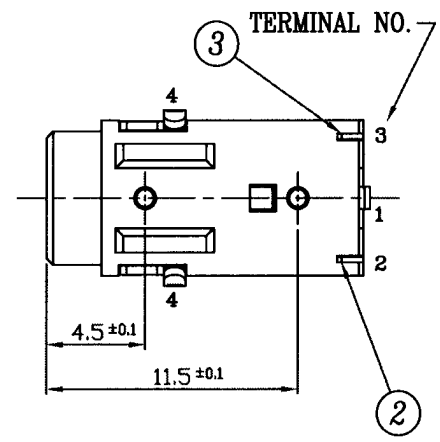
LTR	DESCRIPTION	DATE	APPROVED
VER.1	Replace old version issued on 12-09-2005	16-08-2010	K.F.IM



PC BOARD HOLE LAYOUT (Tols:±0.1)
(VIEW FROM DIRECTION OF INSERTION TO PCB)

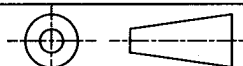


CIRCUIT DIAGRAM



LET	PART NAME	QTY	MATERIAL	REMARK
5	BODY	1	PA66/GF RESIN	SEE TABLE
4	CHIP SPRING	1	PBs 0.4t	Ag-PLATED
3	RING SPRING #3	1	PBs 0.25t	Ag-PLATED
2	RING SPRING #2	1	PBs 0.25t	Ag-PLATED
1	SLEEVE SPRING	1	PBs 0.25t	Ag-PLATED

TOLERANCES
 X ≤ 5 = ± 0.2
 X > 5 = ± 0.3
 ANGULAR = ± ---
DO NOT SCALE DWG.
FINISHED
 _ _ _ _ _

PART NAME Ø3.5 EARPHONE JACK		DWG NO. VER.1 MJ-2135
MATL AS SHOWN IN TABLE		SCALE 3/1 mm
DATE 16-08-2010		DRN / APPD. Y.H.TSANG/K.F.IM